

APPROVED	O.G. FIG.	
BY	CLASS	SUBCLASS
DRAFTSMAN		

Title: Flip chip-in-leadframe package and process

Inventor: Pendse et al.  
Appl. No. 09/802,443

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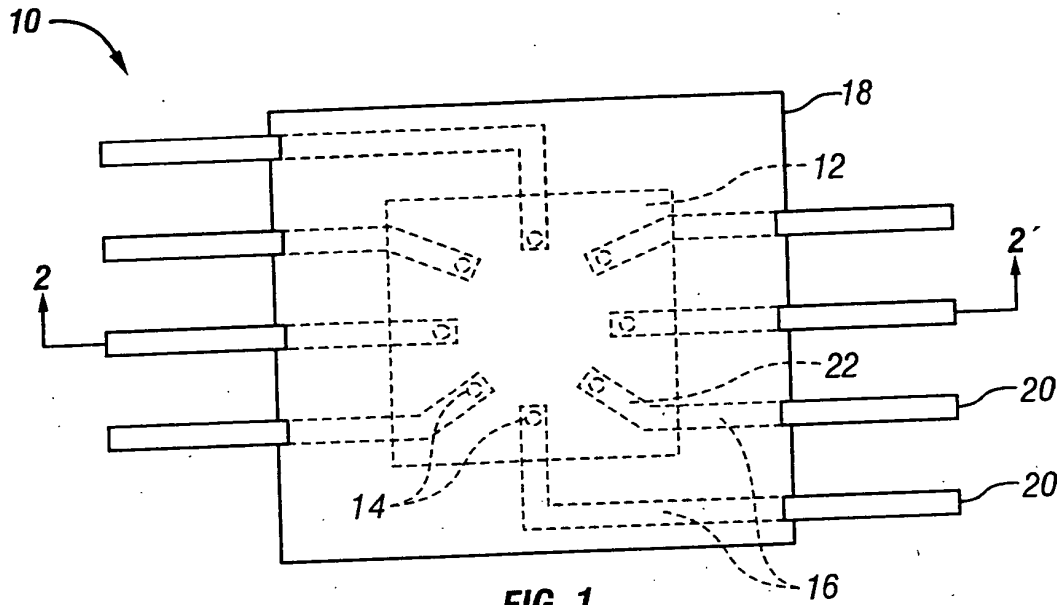


FIG. 1

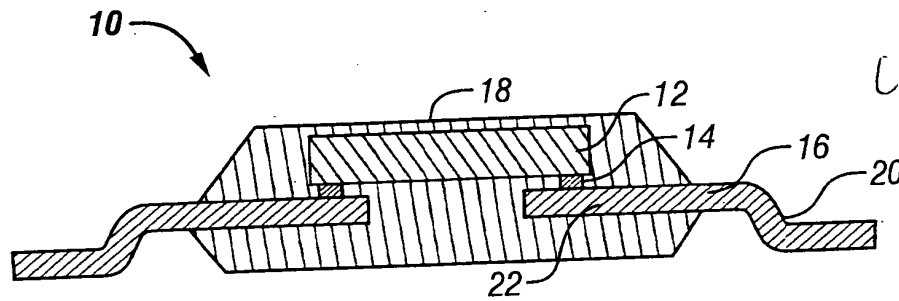


FIG. 2

*Cavity down*  
*up*

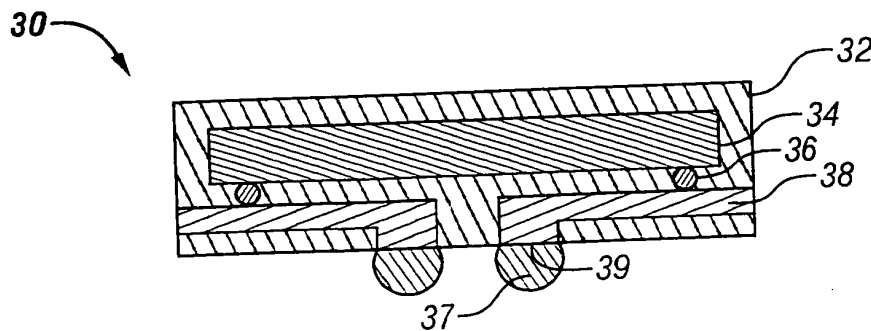


FIG. 3

*Cavity down*

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